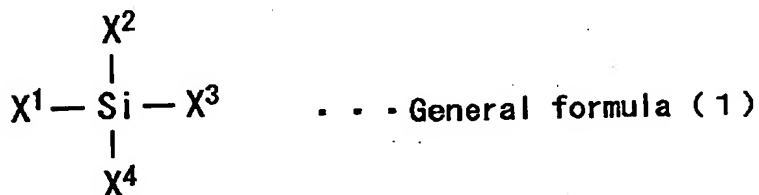


What is claimed is:

1. An adhesive comprising a resin component, a metal chelate, and a silane coupling agent,

wherein said resin component comprises a thermosetting resin and said silane coupling agent comprises a silane compound represented by general formula (1):



wherein at least one of substituents X^1 through X^4 is an alkoxy group.

2. The adhesive according to claim 1, wherein said alkoxy group is a methoxy group.

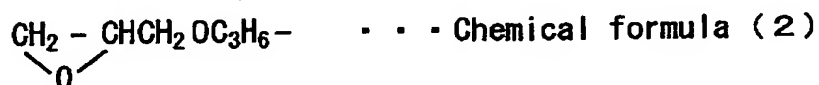
3. The adhesive according to claim 1, wherein said alkoxy group is an ethoxy group.

4. The adhesive according to claim 1, wherein at least one of the substituents X^1 through X^4 of said silane compound is a substituent other than an alkoxy group and at least one of said substituents other than the alkoxy group has an epoxy

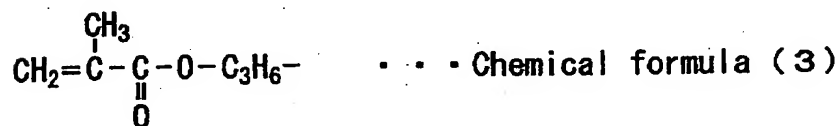
ring.

5. The adhesive according to claim 1, wherein at least one of the substituents X^1 through X^4 of said silane compound is a substituent other than an alkoxy group and at least one of said substituents other than the alkoxy group has an vinyl group.

6. The adhesive according to claim 4, wherein said substituent having the epoxy ring is a γ -glycidoxypropyl group represented by chemical formula (2):



7. The adhesive according to claim 5, wherein said substituent having the vinyl group is a γ -methacryloxypropyl group represented by chemical formula (3):



8. The adhesive according to claim 1, wherein an amount of said metal chelate is from 0.1 parts by weight to 20 parts by weight with respect to 100 parts by weight of said resin component and an amount of said silane coupling agent is from 0.1 parts by weight to 35 parts by weight with respect to 100 parts by weight of said resin component.

9. The adhesive according to claim 1, wherein said resin component further includes a thermoplastic resin and an amount of said thermoplastic resin is 10 parts by weight or more with respect to 100 parts by weight of said thermosetting resin.

10. The adhesive according to claim 8, wherein said resin component further includes a thermoplastic resin and an amount of said thermoplastic resin is 10 parts by weight or more with respect to 100 parts by weight of said thermosetting resin.

11. The adhesive according to claim 1, wherein said thermosetting resin is an epoxy resin.

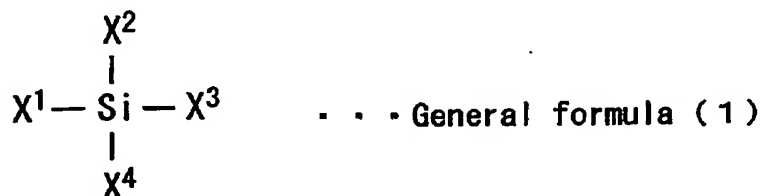
12. The adhesive according to claim 11, wherein the epoxy resin is an alicyclic epoxy resin.

13. The adhesive according to claim 1, wherein said metal chelate comprises an aluminum chelate as a major constituent.

14. The adhesive according to claim 8, wherein said metal chelate comprises an aluminum chelate as a major constituent.

5 15. An adhesive film obtainable by forming an adhesive into a sheet, the adhesive comprising a resin component, a metal chelate, and a silane coupling agent,

wherein said resin component includes a thermosetting resin, and said silane coupling agent is composed of a silane
10 compound represented by general formula (1):



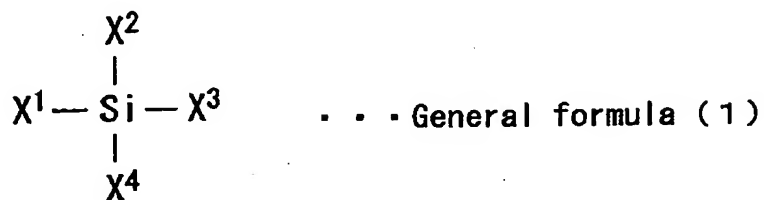
wherein at least one of substituents X^1 through X^4 is an alkoxy group.

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16. An electric device comprising a semiconductor chip and a substrate, wherein an adhesive is disposed between said semiconductor chip and said substrate and is cured by heating, the adhesive comprising a resin component, a metal chelate, and
20 a silane coupling agent,

wherein said resin component comprises a thermosetting

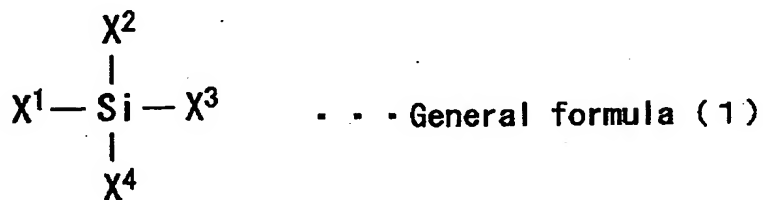
resin and said silane coupling agent comprises a silane compound represented by general formula (1):



5 wherein at least one of substituents X^1 through X^4 is an alkoxy group.

10 17. An electric device comprising a glass substrate and a substrate, wherein an adhesive is disposed between said glass substrate and said substrate and is cured by heating, the adhesive comprising a resin component, a metal chelate, and a silane coupling agent,

15 wherein said resin component comprises a thermosetting resin and said silane coupling agent comprises a silane compound represented by general formula (1):



wherein at least one of substituents X^1 through X^4 is an alkoxy

group.

18. The adhesive according to claim 1, wherein the metal chelate is microcapsulated.

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19. The adhesive according to claim 18, wherein the metal chelate is a powder or liquid.

20. The adhesive according to claim 18, wherein
10 microcapsules are formed as absorbent resin particles and dispersed in the adhesive.

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